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(54) Title: MOLDING A FLUID FLOW STRUCTURE

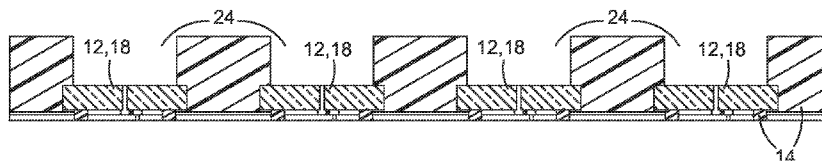


FIG. 10

(57) Abstract: In one example, a process for making a micro device structure includes molding a micro device in a monolithic body of material and forming a fluid flow passage in the body through which fluid can pass directly to the micro device.